AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application.

Listing of claims:

- 1. (Currently Amended) An oxygen-free copper alloy eontaining comprising oxygen 1 10 ppm of the alloy weight, characterized in that wherein the alloy contains, in order to improve temperature resistance, comprises magnesium between 30 180 ppm of the alloy weight and that the electroconductivity of the alloy has an electroconductivity of [[is]] at least 100% International Anneal Copper Standard (IACS)[[,]] in order to improve temperature resistance preferably at least 101% IACS.
- 2. (Currently Amended) [[An]] The oxygen-free copper alloy according to claim 1, eharacterized in that wherein the alloy contains comprises at least 50 ppm of magnesium for over 50 ppm.
- 3. (Currently Amended) [[An]] The oxygen-free copper alloy according to claim 1 or 2, characterized in that, wherein the alloy contains comprises at least 150 ppm of magnesium not more than 150 ppm.
- 4. (Currently Amended) [[An]] The oxygen-free copper alloy according to any of the preceding claims, characterized in that claim 1, wherein the alloy contains comprises at most 5 ppm oxygen not more than 5 ppm, preferably 1 3 ppm.
- 5. (Currently Amended) [[An]] The oxygen-free copper alloy according to any of the preceding claims, characterized in that claim 1, wherein the alloy has a half-softening temperature with a 40% degree of deformation [[is]] of at least 340° C[[,]] preferably at least 380° C.
- 6. (Currently Amended) [[An]] The oxygen-free copper alloy according to any of the preceding claims, characterized in that claim 1, wherein the alloy has a half-

softening temperature with a 94% degree of deformation [[is]] at least 300° C[[,]] preferably at least 335° C.

- 7. (Currently Amended) [[An]] The oxygen-free copper alloy according to any of the preceding claims, characterized in that claim 1, wherein the alloy further contains comprising as impurities phosphorus, silicon and sulfur.
- 8. (Currently Amended) The oxygen-free copper alloy use of copper manufactured according to any of the claims 1 7 claim 1, wherein the alloy is used in commutators of electric motors where there is required a good temperature resistance and a good electroconductivity or thermal conductivity.
- 9. (Currently Amended) The oxygen-free copper alloy use of copper manufactured according to any of the claims 1 7 claim 1, wherein the alloy is used in a tip of a welding electrode where there is required a good temperature resistance and a good electroconductivity or thermal conductivity.
- 10. (Currently Amended) The <u>oxygen-free copper alloy use of copper manufactured</u> according to any of the claims 1—7 claim 1, wherein the alloy is used in generator profiles where there is required a good temperature resistance and a good electroconductivity or thermal conductivity.
- 11. (Currently Amended) The <u>oxygen-free copper alloy use of copper manufactured</u> according to any of the claims 1—7 claim 1, wherein the alloy is used in generator flat bars where there is required a good temperature resistance and a good electroconductivity or thermal conductivity.
- 12. (New) The oxygen-free copper alloy according to claim 1, wherein the electroconductivity is at least 101% IACS.
- 13. (New) The oxygen-free copper alloy according to claim 4, wherein the alloy comprises 1-3 ppm oxygen.

- 14. (New) The oxygen-free copper alloy according to claim 5, wherein the half-softening temperature is at least 380°C.
- 15. (New) The oxygen-free copper alloy according to claim 6, wherein the half-softening temperature is at least 335°C.